

Form PTO-1449

Attorney Docket No.
62020-1290Serial No.
10/699,287

INFORMATION DISCLOSURE CITATION

Applicant
Mule', et al.Filing Date
10/31/03Group
TBD

(Use several sheets if necessary)

U.S. PATENT DOCUMENTS

| Examiner Initials | Item | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate |
|----------------------|------|--------------------|----------|---------------------|-------|----------|-------------------------------|
| /M.D./ | A | 4,380,365 | 4/19/83 | Gross | 350 | 96.18 | 5/23/79 |
| | B | 5,046,800 | 9/10/91 | Blyler, Jr., et al. | 385 | 131 | 10/9/90 |
| | C | 5,130,356 | 7/14/92 | Feuerherd, et al. | 524 | 96 | 2/1/90 |
| | D | 5,302,656 | 4/12/94 | Kohara, et al. | 524 | 579 | 4/10/91 |
| | E | 5,359,208 | 10/25/94 | Katsuki, et al. | 257 | 82 | 2/26/93 |
| | F | 5,454,196 | 7/18/95 | Ohkawa, et al. | 522 | 100 | 7/1/94 |
| | G | 5,462,995 | 10/31/95 | Hosaka, et al. | 525 | 332.1 | 6/9/92 |
| | H | 5,581,414 | 12/3/96 | Snyder | 359 | 819 | 2/22/93 |
| | I | 5,896,479 | 4/20/99 | Vladic | 385 | 59 | 4/9/97 |
| | J | 6,022,498 | 2/8/00 | Buazza, et al. | 264 | 1.38 | 4/19/96 |
| /M.D./ | K | 6,039,897 | 3/21/00 | Lochhead, et al. | 264 | 1.24 | 8/28/97 |

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| /M.D./ | L | Chen, et al.; Fully Embedded Board-Level Guided-Wave Optoelectronic Interconnects; June, 2000; Proceedings of IEEE, Vol. 88, No. 6; pp 780-793 |
| /M.D./ | M | Wiesmann, et al.; Singlemode Polymer Waveguides for Optical Backplanes; December 5, 1996; Electronics Letters, Vol. 32, No. 25; pp 2329-2330 |
| /M.D./ | N | Barry, et al.; Highly Efficient Coupling Between Single-Mode Fiber and Polymer Optical Waveguides; August, 1997; IEEE Transactions on Components, Packaging, and Manufacturing Technology - Part B, Vol. 20, No. 3; pp 225-228 |
| /M.D./ | O | Lee, et al.; Fabrication of Polymeric Large-Core Waveguides for Optical Interconnects Using a Rubber Molding Process; January, 2000; IEEE Photonics Technology Letters, Vol. 12, No. 1; pp 62-64 |
| /M.D./ | P | Schneider, et al.; Electro-Optical Printed Circuit Board (EOPCB); 2000 Electronic Components and Technology Conference; pp 749-753 |
| /M.D./ | Q | Mederer, et al.; 3Gb/s Data Transmission With GaAs VCSELs Over PCB Integrated Polymer Waveguides. September, 2001; IEEE Photonics Technology Letters, Vol. 13, No. 9; pp 1032-1034 |

* EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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| /M.D./ | R | 6,156,394 | 12/5/00 | Schultz Yamasaki, et al. | 427 | 536 | 4/17/98 |
| | S | 6,206,673 | 3/27/01 | Lipscomb, et al. | 425 | 174.4 | 5/30/95 |
| | T | 6,253,004 | 6/26/01 | Lee, et al. | 385 | 31 | 7/9/99 |
| | U | 6,259,567 | 7/10/01 | Brown, et al. | 359 | 668 | 11/23/98 |
| | V | 6,262,414 | 7/17/01 | Mitsuhashi | 250 | 216 | 7/27/99 |
| | W | 6,272,275 | 8/7/01 | Cortright, et al. | 385 | 129 | 6/25/99 |
| | X | 6,281,508 | 8/28/01 | Lee, et al. | 250 | 396 | 2/8/99 |
| | Y | 6,432,328 | 8/13/02 | Hamanaka, et al. | 264 | 1.36 | 1/10/01 |
| /M.D./ | Z | 6,500,603 | 12/31/02 | Shioda | 430 | 321 | 11/9/00 |
| | AA | | | | | | |
| | BB | | | | | | |

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| /M.D./ | CC | Schröder, et al.; Polymer Optical Interconnects for PCB; 2001; Session 13: Photonic Polymers II; pp 337-343 |
| /M.D./ | DD | Glukh, et al.; High performance Polymeric Materials for Waveguide Applications; August, 2000; SPIE - The International Society for Optical Engineering, Infrared, Nonlinear, and Power Limiting Organics, San Diego, Volume 4106; pp 1-11 |
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| /M.D./ | FF | Bakir, et al.; Sea of Dual Mode Polymer Pillar I/O Interconnections for Gigascale Integration; 2003; IEEE International Solid State Circuits Conference; 8 pages |
| /M.D./ | GG | Beuret, et al.; Microfabrication of 3D Multidirectional Inclined Structure by UV lithography and Electroplating; Micro Electro Mechanical Systems, 1994, MEMS'94, Proceedings, IEEE Workshop on January 25-28, 1994; pp 81-85 |
| /M.D./ | HH | Wang, et al.; Studies on A Novel Flip-Chip Interconnect Structure-Pillar Bump; Electronic Components and Technology Conference, 2001, Proceedings, 51st, 29 May-1, June 2001; pp 945-949 |

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| | II | | | | | | |
| | JJ | | | | | | |
| | KK | | | | | | |

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|--------|----|---|
| /M.D./ | LL | Bakir, et al.; Sea of Polymer Pillars: Dual-Mode Electrical Optical Input/Output Interconnections; in Proc. of Int. Interconnect Technology Conference; pp. 77-79; 2003 |
| /M.D./ | MM | Bakir, et al.; Sea of Polymer Pillars: Compliant Wafer-Level Electrical-Optical Chip I/O Interconnections; IEEE Photonics Technology Letters, Vol. 15, No. 11, November 2003; pp 1567-1569 |
| /M.D./ | NN | Bakir, et al.; Optical Transmission of Polymer Pillars for Chip I/O Optical Interconnections; IEEE Photonics Technology Letters, Vol. 16, No. 1, January 2004; pp 117-119 |
| /M.D./ | OO | Chandrasekhar, et al.; Modeling and Characterization of the Polymer Stud Grid Array (PSGA) Package: Electrical, Thermal and Thermo-Mechanical Qualification; IEEE Transactions on Electronics Packaging Manufacturing, Vol. 26, No. 1, January 2003; pp 54-67 |
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